Appl. No. 09/632,425 Amdt. dated December 9, 2003 Amendment under 37 CFR 1.116 Expedited Procedure Examining Group 2829

## **REMARKS/ARGUMENTS**

Claims 1-19 and 21-26 are pending. Claim 20 is canceled without prejudice.

Claim 25 is amended. No new matter has been introduced. Applicants believe the claims comply with 35 U.S.C. § 112.

Applicants note with appreciation the allowance of claims 1-19 and 21-24. Claim 25 as amended recites forming a surface sensitive silicon oxide layer as a lining layer over the substrate having the at least one gap, which is disclosed in the specification at page 15, lines 15-17. Accordingly, Applicants respectfully request withdrawal of the rejection of claims 25 and 26 under 35 U.S.C. § 112, first paragraph.

## **CONCLUSION**

In view of the foregoing, Applicants believe all claims now pending in this Application are in condition for allowance and an action to that end is respectfully requested.

If the Examiner believes a telephone conference would expedite prosecution of this application, please telephone the undersigned at 650-326-2400.

Respectfully submitted,

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